Docket No.

279784US2PCT

# IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:

Takamaro KIKKAWA, et al.

SERIAL NO:

10/553,994

GAU:

FILED:

October 20, 2005

**EXAMINER:** 

FOR:

SEMICONDUCTOR DEVICE

## INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

COMMISSIONER FOR PATENTS ALEXANDRIA, VIRGINIA 22313

SIR:

Applicant(s) wish to disclose the following information.

#### REFERENCES

The applicant(s) wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.

A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

### **RELATED CASES**

Attached is a list of applicant's pending application(s), published application(s) or issued patent(s) which may be related to the present application. In accordance with the waiver of 37 CFR 1.98 dated September 21, 2004, copies of the cited pending applications are not provided. Cited published and/or issued patents, if any, are listed on the attached PTO form 1449.

A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

#### CERTIFICATION

☐ Each item of information contained in this information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.

□ No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

## DEPOSIT ACCOUNT

Please charge any additional fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit account number <u>15-0030</u>. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND, MAIER & NEUSTADT, P.C.

Marvin J. Spivak

Registration No. 24,913

Customer Number

22850

Tel. (703) 413-3000 Fax. (703) 413-2220 (OSMMN 05/03)

Surinder Sachar

TO NITE TO THE 7: (Registration No. 34,423

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	AO	2001-326328	11/22/01	JP (with English abstract)				NO	
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U.S. PCT Application Serial No: 10/553,994

Filed: October 20, 2005

Takamaro KIKKAWA, et al.

Docket No. 279784 US

## STATEMENT OF RELEVANCY

- 1) References AO AP & AW AY have been cited in the International Search Report. A copy of these references is being submitted herewith.
- 2) References have been cited in the corresponding Search Report. A copy of these references is being submitted herewith.
- 3) References are discussed in the specification. A copy of these references is being submitted herewith.
- 4) Reference AZ is additional prior art known to Applicant. A copy of this reference is being submitted herewith.